

List of Current Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-32 (Cancelled).

33. (Currently Amended) The method as claimed in claim ~~[[31]]~~ 65, further comprising the step of:

applying solder paste to solder contact surfaces provided on the second side of the circuit board for a populating of the second side of the circuit board with at least one SMD-component, wherein:

following populating of the second side of the circuit board with the SMD-component, it is soldered, together with the connection wire of the THT-component, in the reflow oven.

34. (Currently Amended) The method as claimed in claim ~~[[32]]~~ 66, further comprising the step of:

applying solder paste to solder contact surfaces provided on the second side of the circuit board for a populating of the second side of the circuit board with at least one SMD-component, wherein:

following populating of the second side of the circuit board with the SMD-component, it is soldered, together with the connection wire of the THT-component, in the reflow oven.

35. (Currently Amended) The method as claimed in claims ~~[[31]]~~ 65, wherein:

the first side of the circuit board is populated with at least one SMD-component.

36. (Currently Amended) The method as claimed in ~~claims 32~~ claim 66, wherein:

the first side of the circuit board is populated with at least one SMD-component.

37. (Previously presented) The method as claimed in claim 35, further comprising the steps of:

printing of solder paste on the first side of the circuit board;
populating of the first side with SMD-components;
soldering the SMD-components of the first side in the reflow oven;
populating of the first side with at least one THT-component;
printing of solder paste on the second side;
populating the second side with SMD-components, and
soldering SMD-components of the second side and the one or more THT-components in the reflow oven.

Claims 38 - 40 (Cancelled).

41. (Previously presented) The method as claimed in claim 37, wherein:
before the populating of the THT-components on the locations to be populated, adhesive for securing the THT-components on the circuit board is applied.

42. (Previously presented) The method as claimed in claim 37, wherein:
on the circuit board and/or on at least one of the THT-components, at least one securement aid is provided, which secures the affected THT-component mechanically on the circuit board following the populating.

43. (Previously presented) The method as claimed in claim 42, wherein:
the securement aid includes a snap-in mechanism.

44. (Previously presented) The method as claimed in claim 35, further comprising the steps:

- printing of solder paste on the first side;
- applying adhesive on the locations of the first side which are to be populated with THT-components;
- populating the first side with SMD-components;
- populating the first side with THT-components;
- soldering the SMD-components of the first side in the reflow oven;
- printing solder paste on the second side;
- populating the second side with SMD-components, and
- soldering the components of the second side and the THT-components in the reflow oven.

Claims 45-48 (Cancelled).

49. (Currently Amended) The method as claimed in claim ~~[[31]]~~ 65, wherein:

- the first side of the circuit board populated with the one or more THT-components is cooled in the reflow oven.

Claims 50 - 53 (Cancelled).

54. (Previously presented) A reflow oven for soldering a circuit board having a first side and a second side and at least one wired, electrical component ("THT-component") having at least one connection wire or connection pin and a housing or casing thermally critical for conventional, automatic soldering technology, comprising:

- means to shield the first side of the circuit board populated with the THT-component during soldering, in the area of a solder contact surface printed

with a solder paste, from a heat or energy feed effecting the soldering of the connection wire of the THT-component emerging at said surface.

55. (Previously presented) A reflow oven for soldering a circuit board having a first side and a second side and at least one wired, electrical component ("THT-component") having at least one connection wire or connection pin and a housing or casing thermally critical for conventional, automatic soldering technology, comprising:

means to shield the first side of the circuit board populated with the THT-component is thermally separated during the soldering, in the area of a solder contact surface printed with a solder paste, from a heat or energy feed effecting the soldering of the connection wire of the THT-component emerging at said surface, wherein:

a temperature difference between the first and second sides of at least 28° C is achievable by suitable means.

56. (Previously presented) A reflow oven as claimed in one of the claims 54, wherein:

the circuit board is arranged such that, during its transport through the reflow oven, the first side of the circuit board populated with the one or more THT-components is shielded, respectively thermally separated, essentially by the circuit board itself from the heat or energy feed acting on the second side of the circuit board for the soldering.

57. (Previously presented) A reflow oven as claimed in one of the claims 55, wherein:

the circuit board is arranged such that, during its transport through the reflow oven, the first side of the circuit board populated with the one or more THT-components is shielded, respectively thermally separated, essentially by the

circuit board itself from the heat or energy feed acting on the second side of the circuit board for the soldering.

58. (Previously presented) The reflow oven as claimed in claim 54, further comprising:

a cooling apparatus provided therein, by means of which the side of the circuit board populated with the one or more THT-components is cooled during the soldering operation.

59. (Previously presented) The reflow oven as claimed in claim 55, further comprising:

a cooling apparatus provided therein, by means of which the side of the circuit board populated with the one or more THT-components is cooled during the soldering operation.

Claims 60 - 64 (Cancelled).

65. (New) A method for populating and soldering a circuit board having a first side and a second side and at least one wired, electrical component ("THT-component") having at least one connection wire or connection pin and a housing or casing thermally critical for conventional, automatic soldering technology, comprising the steps of:

populating the THT-component on the first side of the circuit board, with the connection wire or pin stuck from the first side through a hole and emerging on the second side of the circuit board in the area of a soldering contact surface printed with a solder paste;

placing the circuit board so populated into a reflow oven for the soldering, wherein:

the first side populated with the THT-component is at least partially, essentially shielded from a heat or energy feed effecting the soldering;

the first side of the circuit board populated with the one or more THT-components is shielded, thermally separated, in the reflow oven essentially by the circuit board itself from the heat or energy feed acting on the second side for the soldering; and

in the case of an essentially horizontal arrangement of the circuit board during travel through the reflow oven for the soldering of the THT-components or the THT-component, these or this, as the case may be, are located underneath the circuit board.

66. (New) A method for populating and soldering a circuit board having a first side and a second side and at least one wired, electrical component ("THT-component") having at least one connection wire or connection pin and a housing or casing thermally critical for conventional, automatic soldering technology, comprising the steps of:

populating the THT-component on the first side of the circuit board, with the connection wire or pin stuck from the first side through a hole and emerging on the second side of the circuit board in the area of a soldering contact surface printed with a solder paste; and

placing the circuit board so populated into a reflow oven for the soldering, wherein:

the first side populated with the THT-component is thermally separated from the heat or energy feed acting on the second side of the circuit board for the soldering;

a temperature difference of at least 28°C can be achieved between the first side and the second side;

the first side of the circuit board populated with the one or more THT-components is shielded, thermally separated, in the reflow oven essentially by the circuit board itself from the heat or energy feed acting on the second side for the soldering; and

in the case of an essentially horizontal arrangement of the circuit board during travel through the reflow oven for the soldering of the THT-components or the THT-component, these or this, as the case may be, are located underneath the circuit board.